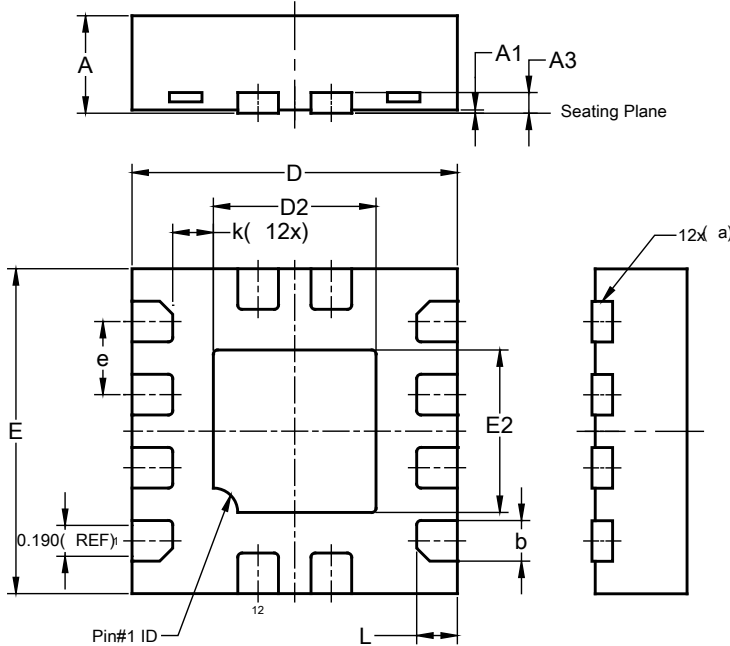


Package Outline Dimensions

U-QFN2020-12 (Type B)

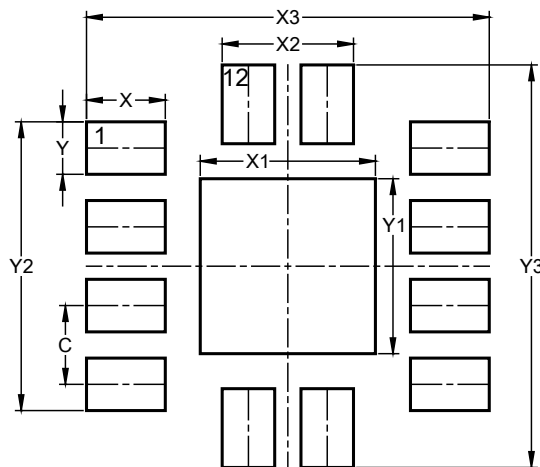


U-QFN2020-12 (Type B)			
Dim	Min	Max	Typ
A	0.55	0.65	0.60
A1	0.00	0.05	0.02
A3	--	--	0.13
b	0.20	0.30	0.25
D	1.95	2.05	2.00
D2	0.90	1.10	1.00
E	1.95	2.05	2.00
E2	0.90	1.10	1.00
e	0.45 BSC		
k	--	--	0.25
L	0.20	0.30	0.25
All Dimensions in mm			

a) Actual shape depending upon manufacturing technology used.

Suggested Pad Layout

U-QFN2020-12 (Type B)



Dimensions	Value (in mm)
C	0.450
X	0.450
X1	1.000
X2	0.750
X3	2.300
Y	0.300
Y1	1.000
Y2	1.650
Y3	2.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.